

Fig. 1 is a cross-sectional view of a multi-layered electronic component assembly. It shows a top layer (1) with a pattern of conductive traces (5) on its bottom surface. A central core (3) is sandwiched between this top layer and a bottom layer (4). The bottom layer (4) also features conductive traces (10) on its bottom surface. A small rectangular component (9) is mounted on the bottom surface of the bottom layer (4). Fig. 2 is a cross-sectional view of a similar assembly, showing a top layer (2) with conductive traces (7A) on its bottom surface. A central core (6) is sandwiched between this top layer and a bottom layer (7B). The bottom layer (7B) has conductive traces (12) on its bottom surface. A small rectangular component (16) is mounted on the bottom surface of the bottom layer (7B). A vertical arrow labeled 'MD' indicates the mounting direction.

FIG. 2

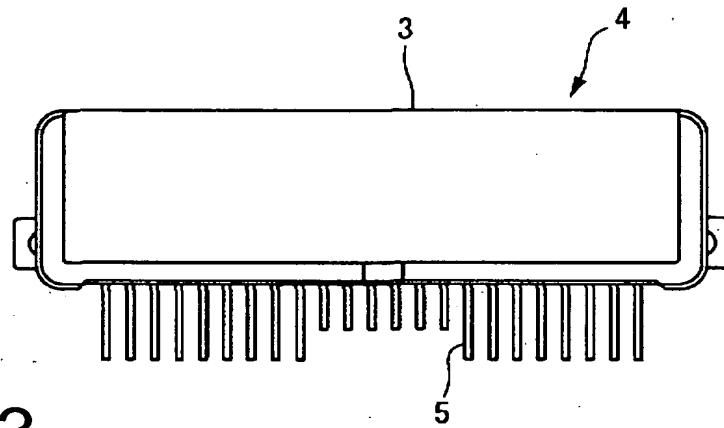


FIG. 3

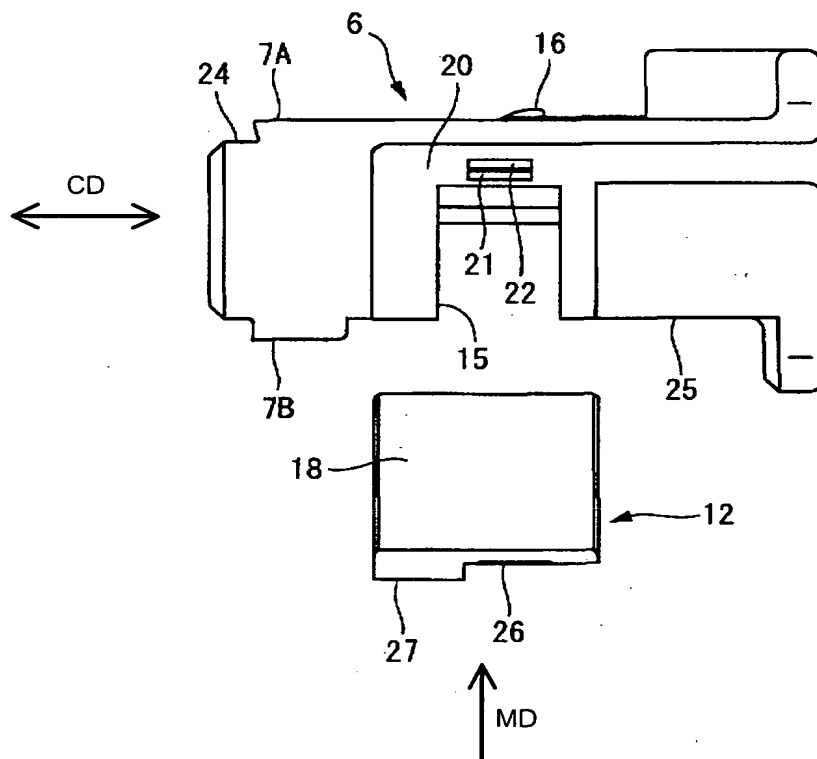


FIG. 4

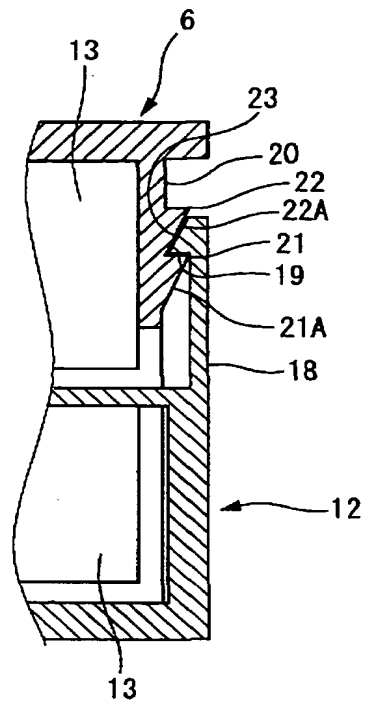


FIG. 5

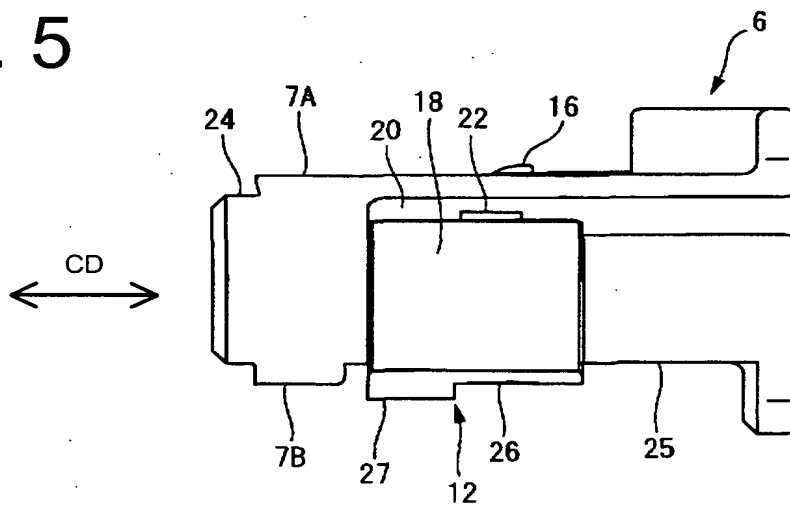


FIG. 6

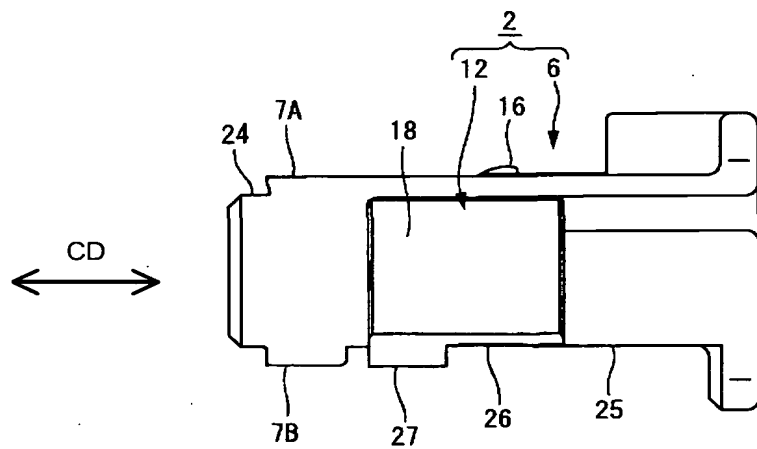


FIG. 7

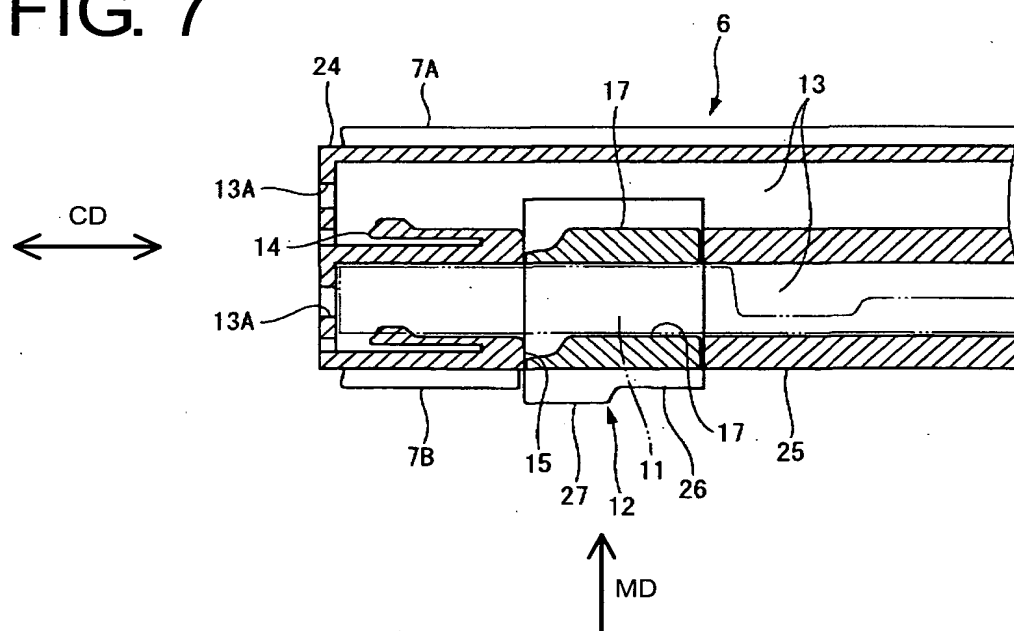


FIG. 8

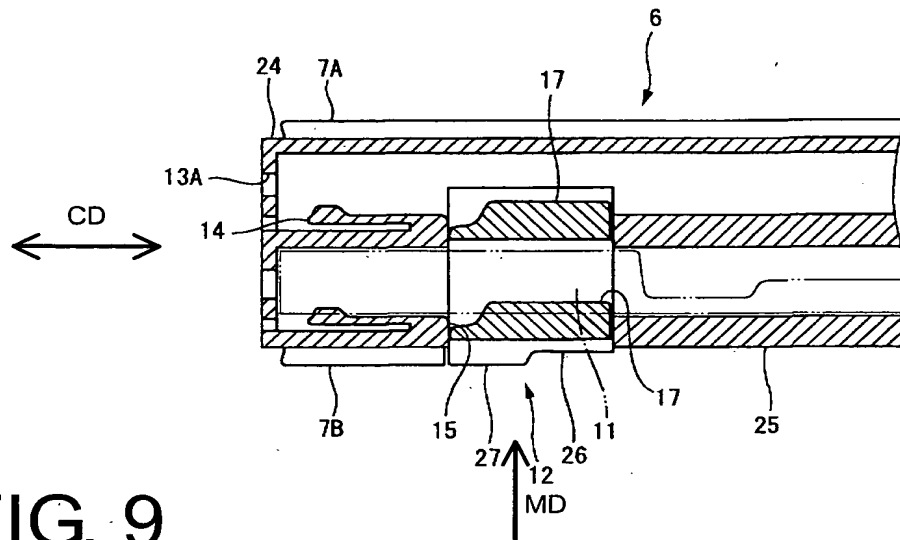


FIG. 9

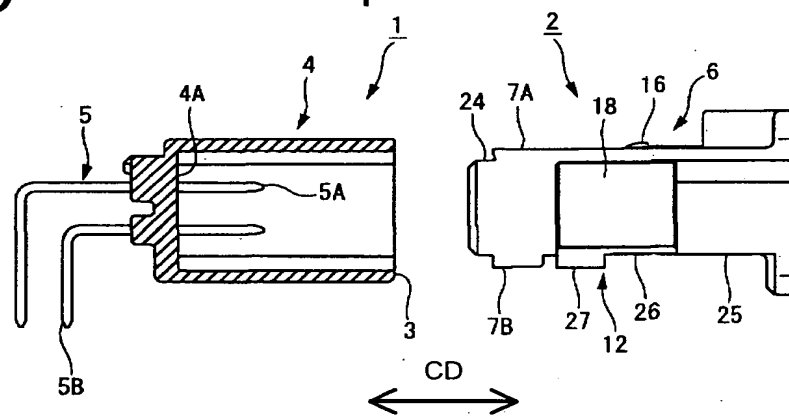


FIG. 10

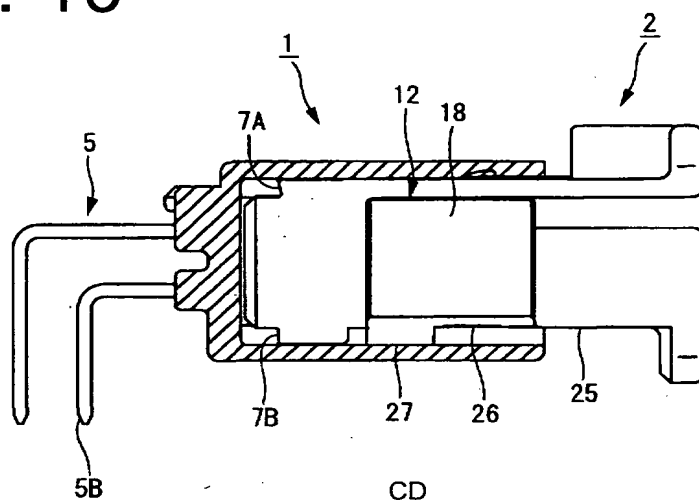


FIG. 11

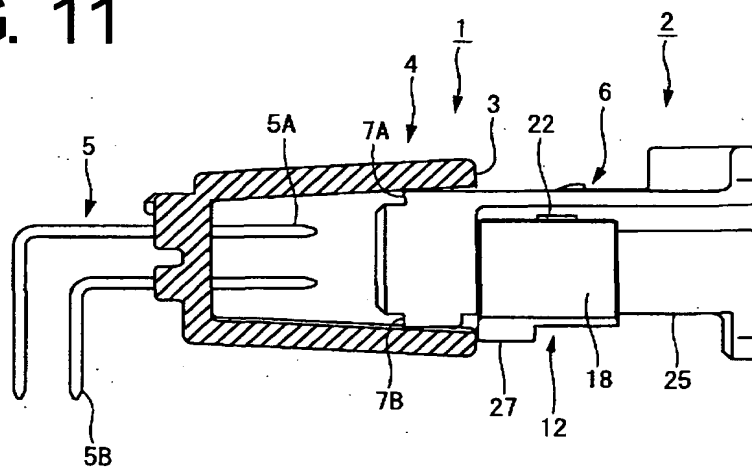


FIG. 12
PRIOR ART

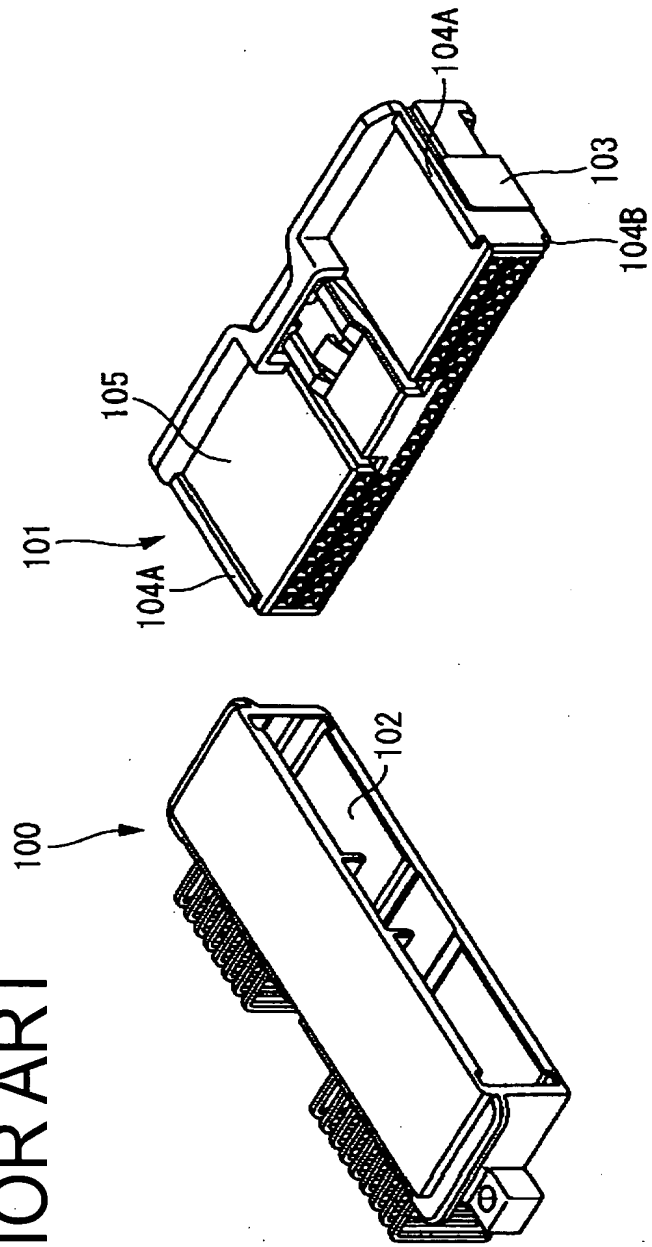


FIG. 13
PRIOR ART

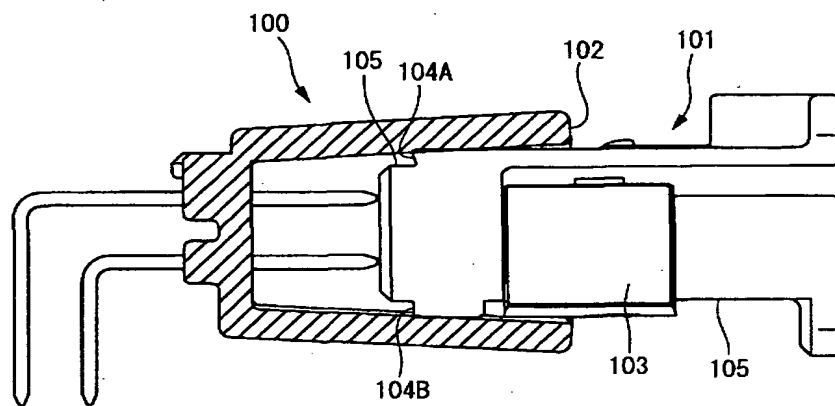


FIG. 14

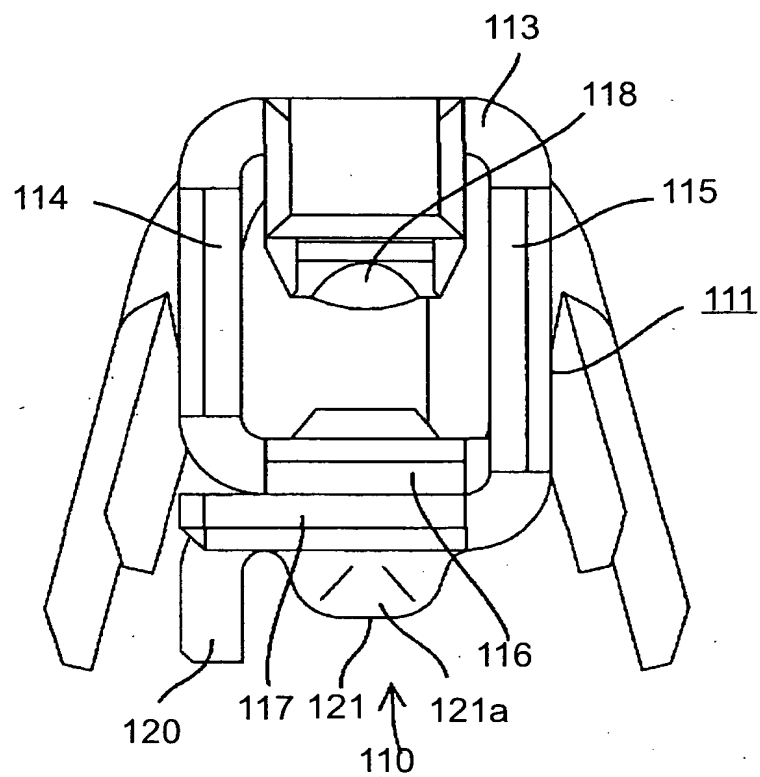


FIG. 15

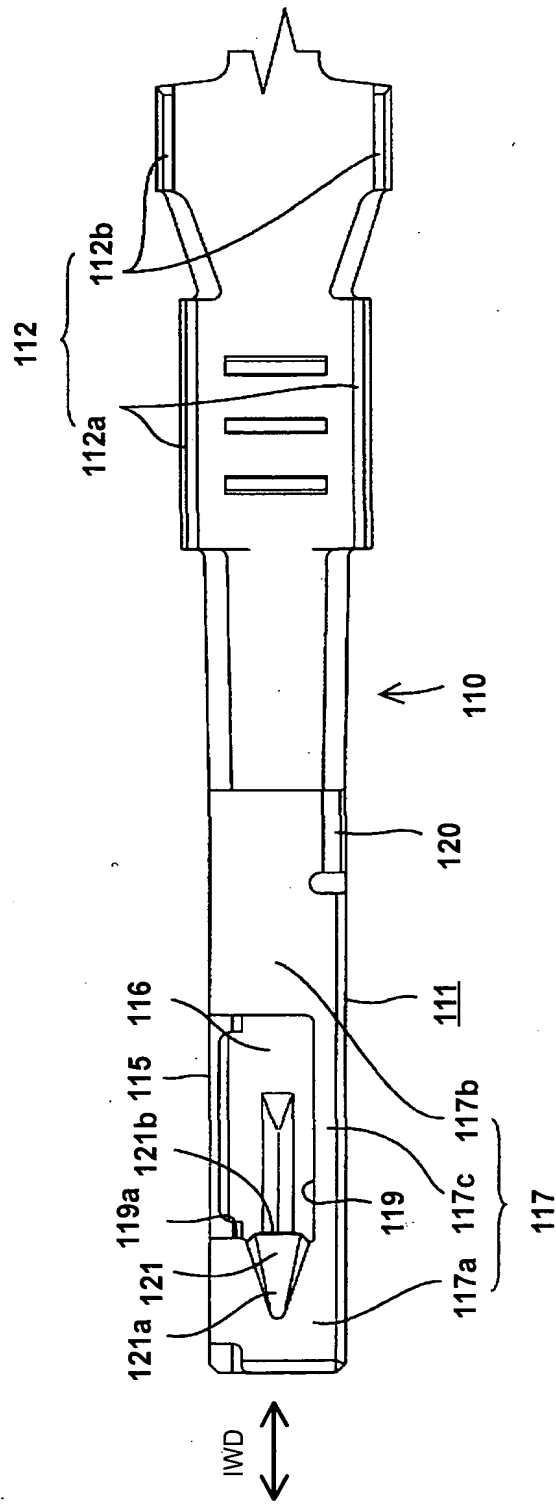


FIG. 16

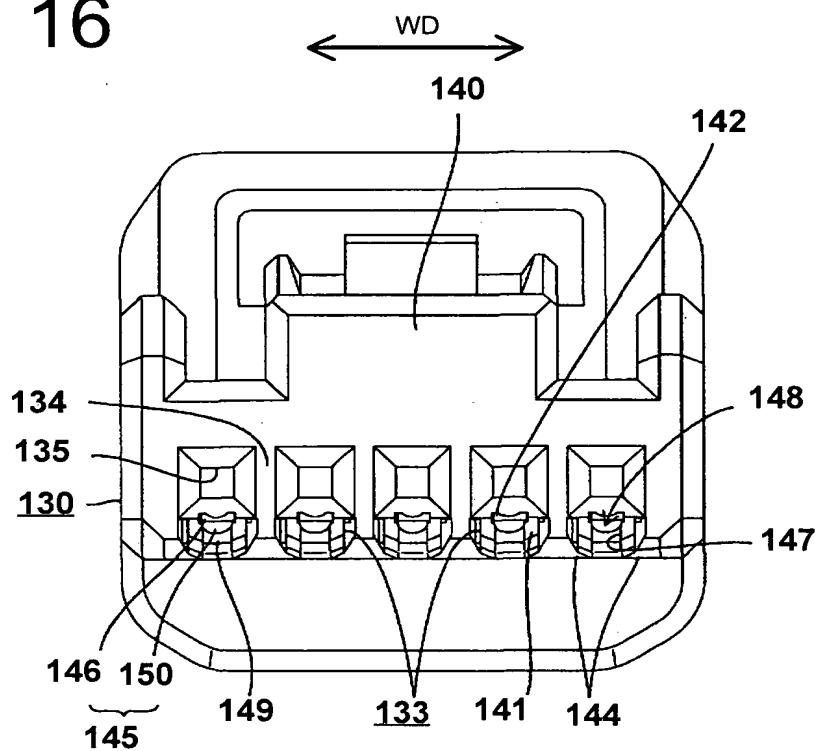


FIG. 18

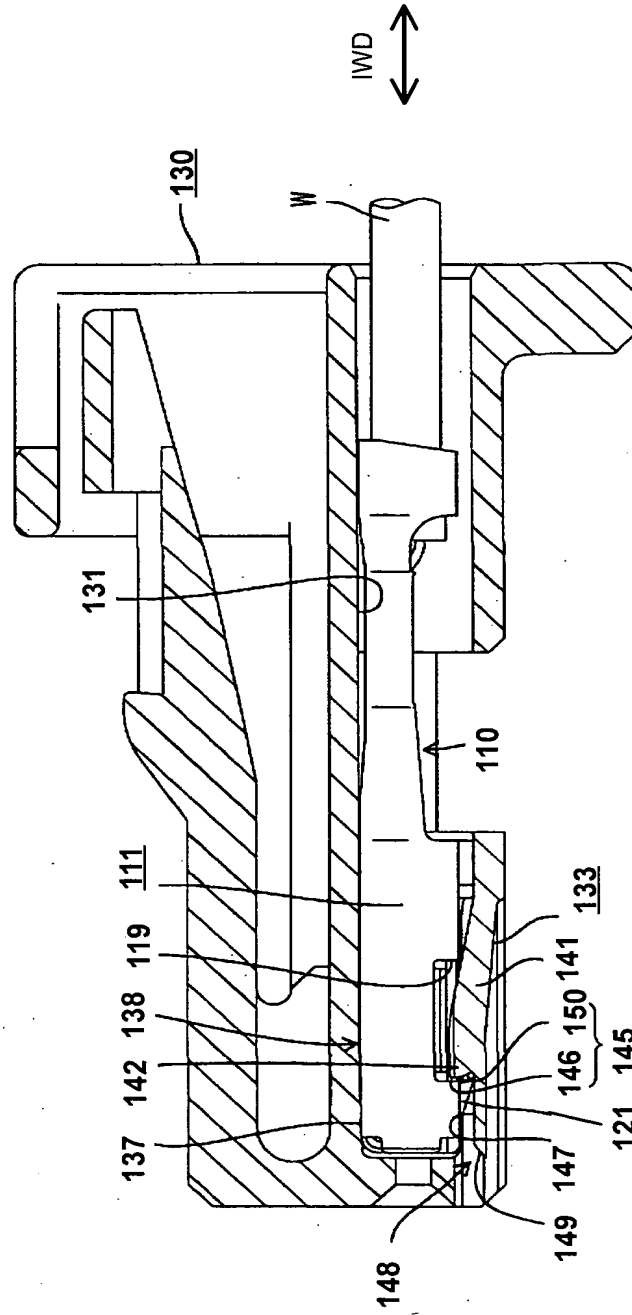
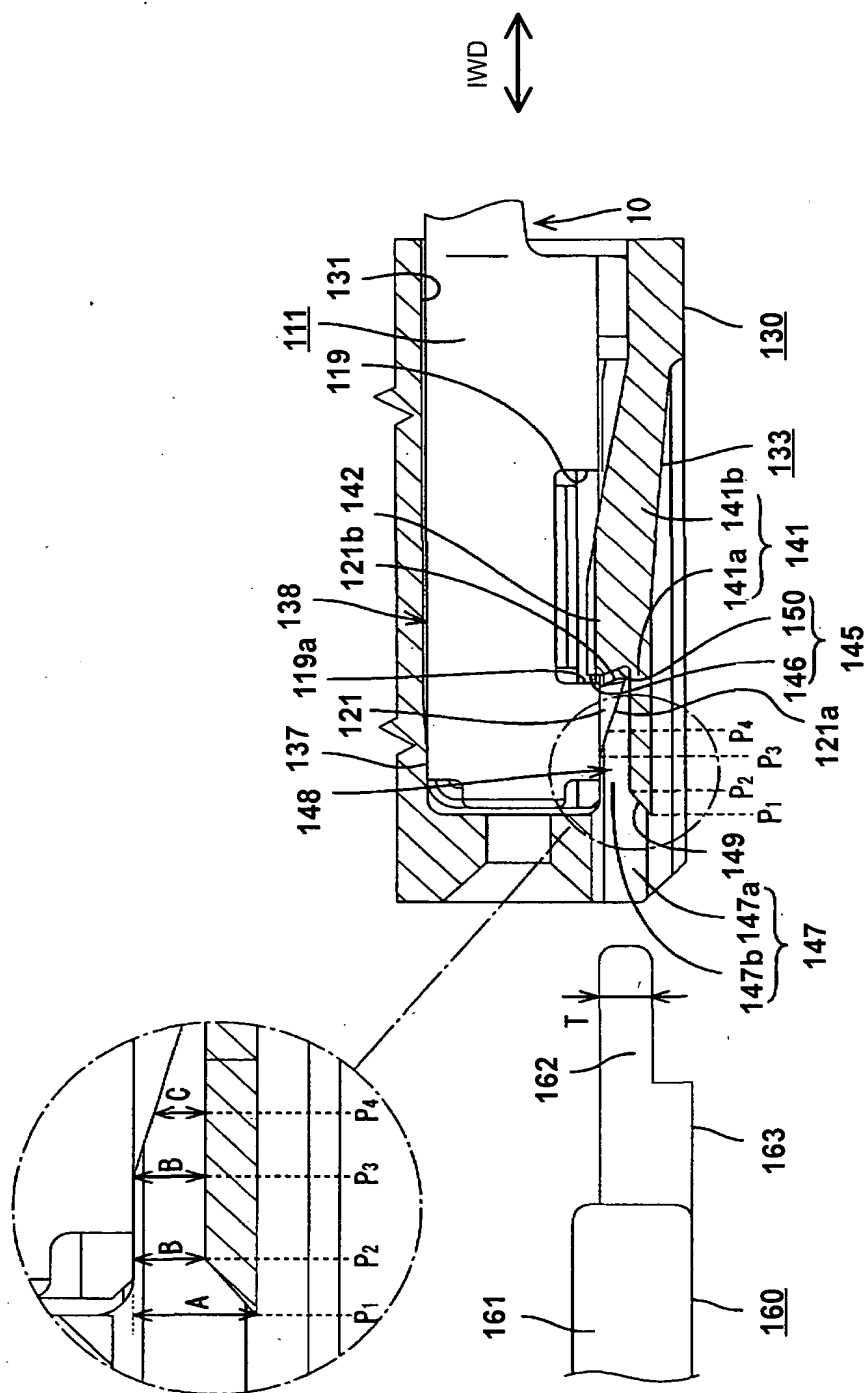


FIG. 19



[illegible]

FIG. 22

